

# DDI(Display Driver IC) Code Information (1/2)

Last Updated : August 2009

**S** **6** X X X X X X X X X X X X X  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

## 1. System LSI (S)

## 2. Large Classification : DDI (6)

### 3. Small Classification

A : STN (Character)	B : STN (Graphic)
C : TFT (Large)	D : TFT (Mobile)
E : OELD	F : TFT (Midsmall)
K : OELD (Large)	L : LED Driver
P : PDI (DUAL)	T : TCON
V : Process Vehicle	

## 4~7.

Serial No.

## 8. Version

A~Z

\*1st Version → X

## 9~10. Mask Option

### - STN (Character)

00~99 : Font

### - STN (Graphic)

Mask Option

### - TFT Device

Mask Option

## 11. " - "

## 12~14. Package Type

### - In Case of PKG

(12) Package Type

A : SDIP	B : BUMP BIZ
C : CHIP BIZ	E : LQFP
J : ELP	K : TR
N : COB	Q : QFP
S : SOP	T : TQFP
W : WAFER	X : ETQFP
Y : FBGA	

## (13) Reserved

- PKG Option

0 : none

1 : Special Handling 1      2 : Special Handling 2

3 : Special Handling 3      4 : Special Handling 4

5 : Special Handling 5      6 : Special Handling 6

A : Test Condition 1      B : Customer Option 1

C : Customer Option 2      D : Customer Option 3

E : Customer Option 4      F : Customer Option 5

G : Customer Option 6      H : Customer Option 7

J : Customer Option 8      K : Customer Option 9

L : Customer Option 10     M : Customer Option 11

N : Customer Option 12     P : Customer Option 13

Q : Customer Option 14     R : Customer Option 15

S : Customer Option 16     T : Customer Option 17

U : Customer Option 18     V : Customer Option 19

W : Customer Option 20     X : Customer Option 21

- WAFER

0 : BUMP

1 : NO BUMP

(14) Packing

### - In Case of TAB / COF

(12)(13) Film Type

00~49 → TAB

50~99 → COF

(14) Revision

1st Version → X

# DDI(Display Driver IC) Code Information (2/2)

Last Updated : August 2009

<u>S</u>	<u>6</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

## 15. Back Lap

- 0 : No Grinding
- 1 : 250±10um
- 2 : 180±10um (Polishing / Grinding)
- 3 : 140±10um
- 5 : 200±10um
- 6 : 220±10um
- 7 : 170±10um (Polishing / Grinding)
- 8 : 300±10um (CHIP BIZ)
- 9 : 280±10um
- A : 300±10um
- C : 300±10um (Wafer)
- D : 350±10um
- G : 375±10um (CHIP BIZ)
- J : 425±10um
- K : 400±10um
- L : 450±10um
- M : 470±10um (Wafer)
- N : 470±10um
- R : 350±10um (Wafer)
- U : 610±10um
- V : 500±10um (CHIP BIZ)
- W : 425±10um (Wafer)
- X : 425±10um (CHIP BIZ)
- Y : 470±10um (CHIP BIZ)
- Z : No Grinding (CHIP / Wafer)